Evonik Corporation Compimide® 1224L60 Bismaleimide

Category : Polymer , Thermoset , Polyimide, TS

Material Notes:

Compimide® 1224L60 is a heat-curable formulated bismaleimide resin supplied as a solution in gamma-butyrolactone. It is recommended for the manufacture of printed wiring boards (PWB) via the prepreg route. Compimide® 1224L60 can also be formulated with epoxy resins to improve their temperature resistance.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Evonik-Corporation-Compimide-1224L60-Bismaleimide.php

| Physical Properties | Metric | English | Comments |
|-----------------------|----------------------|----------------------|----------|
| Viscosity | 400 - 700 cP | 400 - 700 сР | |
| | @Temperature 25.0 °C | @Temperature 77.0 °F | |
| | | | |
| Processing Properties | Metric | English | Comments |
| Gel Time | 5.00 - 10.0 min | 5.00 - 10.0 min | |
| | @Temperature 170 °C | @Temperature 338 °F | |

| Descriptive Properties | Value | Comments |
|------------------------|----------|----------|
| Resin Content | 60±2 wt% | |

Contact Songhan Plastic Technology Co.,Ltd.

Website : www.lookpolymers.com Email : sales@lookpolymers.com Tel : +86 021-51131842 Mobile : +86 13061808058 Skype : lookpolymers Address : United North Road 215,Fengxian District, Shanghai City,China